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Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

Product Status	Obsolete
Core Processor	80C51
Core Size	8-Bit
Speed	30/20MHz
Connectivity	UART/USART
Peripherals	POR, PWM, WDT
Number of I/O	32
Program Memory Size	-
Program Memory Type	ROMIess
EEPROM Size	-
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-LCC (J-Lead)
Supplier Device Package	44-PLCC (16.6x16.6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/at80c51ra2-slsul

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5.2 TS80C51Rx2 Enhanced Features

In comparison to the original 80C52, the TS8xC51Rx2 implements some new features, which are:

- The X2 option.
- The Dual Data Pointer.
- The extended RAM.
- The Programmable Counter Array (PCA).
- The Watchdog.
- The 4 level interrupt priority system.
- The power-off flag.
- The ONCE mode.
- The ALE disabling.
- Some enhanced features are also located in the UART and the timer 2.

5.3 X2 Feature

The TS80C51Rx2 core needs only 6 clock periods per machine cycle. This feature called "X2" provides the following advantages:

- Divides frequency crystals by 2 (cheaper crystals) while keeping same CPU power.
- Saves power consumption while keeping same CPU power (oscillator power saving).
- Saves power consumption by dividing dynamically operating frequency by 2 in operating and idle modes.
- Increases CPU power by 2 while keeping same crystal frequency.

In order to keep the original C51 compatibility, a divider by 2 is inserted between the XTAL1 signal and the main clock input of the core (phase generator). This divider may be disabled by software.

5.3.1 Description

The clock for the whole circuit and peripheral is first divided by two before being used by the CPU core and peripherals. This allows any cyclic ratio to be accepted on XTAL1 input. In X2 mode, as this divider is bypassed, the signals on XTAL1 must have a cyclic ratio between 40 to 60%. Figure 5-1 shows the clock generation block diagram. X2 bit is validated on XTAL1÷2 rising edge to avoid glitches when switching from X2 to STD mode. Figure 5-2 shows the mode switching waveforms.



6. Application

Software can take advantage of the additional data pointers to both increase speed and reduce code size, for example, block operations (copy, compare, search ...) are well served by using one data pointer as a 'source' pointer and the other one as a "destination" pointer.

ASSEMBLY LANGUAGE

; Block move using dual data pointers ; Destroys DPTR0, DPTR1, A and PSW ; note: DPS exits opposite of entry state ; unless an extra INC AUXR1 is added 00A2 AUXR1 EQU 0A2H ; 0000 909000MOV DPTR, #SOURCE ; address of SOURCE 0003 05A2 INC AUXR1 ; switch data pointers 0005 90A000 MOV DPTR, #DEST ; address of DEST 0008 LOOP: 0008 05A2 INC AUXR1 ; switch data pointers 000A EO MOVX A, @DPTR ; get a byte from SOURCE 000B A3 INC DPTR ; increment SOURCE address 000C 05A2 INC AUXR1 ; switch data pointers 000E FO MOVX @DPTR, A ; write the byte to DEST 000F A3 INC DPTR ; increment DEST address 0010 70F6JNZ LOOP ; check for 0 terminator 0012 05A2 INC AUXR1 ; (optional) restore DPS

INC is a short (2 bytes) and fast (12 clocks) way to manipulate the DPS bit in the AUXR1 SFR. However, note that the INC instruction does not directly force the DPS bit to a particular state, but simply toggles it. In simple routines, such as the block move example, only the fact that DPS is toggled in the proper sequence matters, not its actual value. In other words, the block move routine works the same whether DPS is '0' or '1' on entry. Observe that without the last instruction (INC AUXR1), the routine will exit with DPS in the opposite state.

There are two additional registers associated with each of the PCA modules. They are CCAPnH and CCAPnL and these are the registers that store the 16-bit count when a capture occurs or a compare should occur. When a module is used in the PWM mode these registers are used to control the duty cycle of the output (See Table 6-8 & Table 6-9)

 Table 6-8.
 CCAPnH: PCA Modules Capture/Compare Registers High

	7	6	5	4	3	2	1	0
Reset value	0	0	0	0	0	0	0	0

 Table 6-9.
 CCAPnL: PCA Modules Capture/Compare Registers Low

CCAPnL Address n = 0 - 4	
11 = 0 +	

CCAP0L=0EAH	
CCAP1L=0EBH	
CCAP2L=0ECH	
CCAP3L=0EDH	
CCAP4L=0EEH	

	7	6	5	4	3	2	1	0
Reset value	0	0	0	0	0	0	0	0

Table 6-10.CH: PCA Counter High

CH Address 0F9H

Н									
		7	6	5	4	3	2	1	0
	Reset value	0	0	0	0	0	0	0	0

Table 6-11. CL: PCA Counter Low

CL

Address 0E9H

	7	6	5	4	3	2	1	0
Reset value	0	0	0	0	0	0	0	0

6.3.1 PCA Capture Mode

To use one of the PCA modules in the capture mode either one or both of the CCAPM bits CAPN and CAPP for that module must be set. The external CEX input for the module (on port 1) is sampled for a transition. When a valid transition occurs the PCA hardware loads the value of the PCA counter registers (CH and CL) into the module's capture registers (CCAPnL and CCAPnH). If the CCFn bit for the module in the CCON SFR and the ECCFn bit in the CCAPMn SFR are set then an interrupt will be generated (Refer to Figure 6-6).



Figure 6-9. PCA PWM Mode



6.3.5 PCA Watchdog Timer

An on-board watchdog timer is available with the PCA to improve the reliability of the system without increasing chip count. Watchdog timers are useful for systems that are susceptible to noise, power glitches, or electrostatic discharge. Module 4 is the only PCA module that can be programmed as a watchdog. However, this module can still be used for other modes if the watchdog is not needed. Figure 6-7 shows a diagram of how the watchdog works. The user preloads a 16-bit value in the compare registers. Just like the other compare modes, this 16-bit value is compared to the PCA timer value. If a match is allowed to occur, an internal reset will be generated. This will not cause the RST pin to be driven high.

In order to hold off the reset, the user has three options:

- 1. Periodically change the compare value so it will never match the PCA timer,
- 2. periodically change the PCA timer value so it will never match the compare values, or
- 3. Disable the watchdog by clearing the WDTE bit before a match occurs and then re-enable it.

The first two options are more reliable because the watchdog timer is never disabled as in option #3. If the program counter ever goes astray, a match will eventually occur and cause an internal reset. The second option is also not recommended if other PCA modules are being used. Remember, the PCA timer is the time base for all modules; changing the time base for other modules would not be a good idea. Thus, in most applications the first solution is the best option.

This watchdog timer won't generate a reset out on the reset pin.



Figure 6-12. UART Timings in Modes 2 and 3



6.4.2 Automatic Address Recognition

The automatic address recognition feature is enabled when the multiprocessor communication feature is enabled (SM2 bit in SCON register is set).

Implemented in hardware, automatic address recognition enhances the multiprocessor communication feature by allowing the serial port to examine the address of each incoming command frame. Only when the serial port recognizes its own address, the receiver sets RI bit in SCON register to generate an interrupt. This ensures that the CPU is not interrupted by command frames addressed to other devices.

If desired, you may enable the automatic address recognition feature in mode 1. In this configuration, the stop bit takes the place of the ninth data bit. Bit RI is set only when the received command frame address matches the device's address and is terminated by a valid stop bit.

To support automatic address recognition, a device is identified by a given address and a broadcast address.

Note: The multiprocessor communication and automatic address recognition features cannot be enabled in mode 0 (i.e. setting SM2 bit in SCON register in mode 0 has no effect).

6.4.3 Given Address

Each device has an individual address that is specified in SADDR register; the SADEN register is a mask byte that contains don't-care bits (defined by zeros) to form the device's given address. The don't-care bits provide the flexibility to address one or more slaves at a time. The following example illustrates how a given address is formed.

To address a device by its individual address, the SADEN mask byte must be 1111 1111b.

For example:

```
SADDR0101 0110b
SADEN1111 1100b
Given0101 01XXb
```

The following is an example of how to use given addresses to address different slaves:

```
Slave A:SADDR1111 0001b

<u>SADEN1111 1010b</u>

Given1111 0X0Xb

Slave B:SADDR1111 0011b

<u>SADEN1111 1001b</u>

Given1111 0XX1b
```





6.5 Interrupt System

The TS80C51Rx2 has a total of 7 interrupt vectors: two external interrupts ($\overline{INT0}$ and $\overline{INT1}$), three timer interrupts (timers 0, 1 and 2), the serial port interrupt and the PCA global interrupt. These interrupts are shown in Figure 6-13.

WARNING: Note that in the first version of RC devices, the PCA interrupt is in the lowest priority. Thus the order in INTO, TF0, INT1, TF1, RI or TI, TF2 or EXF2, PCA.





Each of the interrupt sources can be individually enabled or disabled by setting or clearing a bit in the Interrupt Enable register (See Table 6-17.Table 6-18.). This register also contains a global disable bit, which must be cleared to disable all interrupts at once.

Each interrupt source can also be individually programmed to one out of four priority levels by setting or clearing a bit in the Interrupt Priority register (See Table 6-18.) and in the Interrupt Priority High register (See Table 6-19.). shows the bit values and priority levels associated with each combination.

The PCA interrupt vector is located at address 0033H. All other vector addresses are the same as standard C52 devices.

Table 6-16.	Priority Level Bit Values
-------------	---------------------------

IPH.x	IP.x	Interrupt Level Priority
0	0	0 (Lowest)
0	1	1
1	0	2
1	1	3 (Highest)

A low-priority interrupt can be interrupted by a high priority interrupt, but not by another low-priority interrupt. A high-priority interrupt can't be interrupted by any other interrupt source.

If two interrupt requests of different priority levels are received simultaneously, the request of higher priority level is serviced. If interrupt requests of the same priority level are received simultaneously, an internal polling sequence determines which request is serviced. Thus within each priority level there is a second priority structure determined by the polling sequence.

Table 6-17. IE Register

IE - Interrupt Enable Register (A8h)

7	6		5	4	3	2	1	0		
EA	EC	I	ET2	ES	ET1	EX1	ET0	EX0		
Bit Number	Bit Mnem	nonic	Descrip	otion						
7	EA		Enable A Clear to Set to e If EA=1, clearing	Enable All interrupt bit Clear to disable all interrupts. Set to enable all interrupts. If EA=1, each interrupt source is individually enabled or disabled by setting o clearing its own interrupt enable bit.						
6	EC		PCA int Clear to	errupt enable disable . Set to	bit o enable.					
5	ET2		Timer 2 Clear to Set to e	overflow intern disable timer 2 nable timer 2 o	upt Enable bit 2 overflow interr verflow interrup	rupt. bt.				
4	ES		Serial po Clear to Set to e	Serial port Enable bit Clear to disable serial port interrupt. Set to enable serial port interrupt.						
3	ET1		Timer 1 Clear to Set to e	Timer 1 overflow interrupt Enable bit Clear to disable timer 1 overflow interrupt. Set to enable timer 1 overflow interrupt.						
2	EX1		External Clear to Set to e	External interrupt 1 Enable bit Clear to disable external interrupt 1. Set to enable external interrupt 1.						
1	ET0		Timer 0 Clear to Set to e	Timer 0 overflow interrupt Enable bit Clear to disable timer 0 overflow interrupt. Set to enable timer 0 overflow interrupt.						
0	EX0		External Clear to Set to e	l interrupt 0 En disable extern nable external	able bit al interrupt 0. interrupt 0.					

Reset Value = 0000 0000b

Bit addressable





Table 6-18.IP RegisterIP - Interrupt Priority Register (B8h)

7	6	5	4	3	2	1	0		
-	PPC	PT2	PS	PT1	PX1	PT0	PX0		
Bit Number	Bit Mnemo	nic Descr	ption						
7	-	Reser The va	Reserved The value read from this bit is indeterminate. Do not set this bit.						
6	PPC	PCA in Refer t	CA interrupt priority bit Refer to PPCH for priority level.						
5	PT2	Timer Refer t	Timer 2 overflow interrupt Priority bit Refer to PT2H for priority level.						
4	PS	Serial Refer t	Serial port Priority bit Refer to PSH for priority level.						
3	PT1	Timer Refer t	Timer 1 overflow interrupt Priority bit Refer to PT1H for priority level.						
2	PX1	Extern Refer t	External interrupt 1 Priority bit Refer to PX1H for priority level.						
1	PT0	Timer Refer t	Timer 0 overflow interrupt Priority bit Refer to PT0H for priority level.						
0	PX0	Extern Refer t	External interrupt 0 Priority bit Refer to PX0H for priority level.						

Reset Value = X000 0000b

Bit addressable



6.9 ONCE[™] Mode (ON Chip Emulation)

The ONCE mode facilitates testing and debugging of systems using TS8xC51Rx2 without removing the circuit from the board. The ONCE mode is invoked by driving certain pins of the TS80C51Rx2; the following sequence must be exercised:

- Pull ALE low while the device is in reset (RST high) and PSEN is high.
- Hold ALE low as RST is deactivated.

While the TS80C51Rx2 is in ONCE mode, an emulator or test CPU can be used to drive the circuit Table 26. shows the status of the port pins during ONCE mode.

Normal operation is restored when normal reset is applied.

ALE	PSEN	Port 0	Port 1	Port 2	Port 3	XTAL1/2
Weak pull-up	Weak pull-up	Float	Weak pull-up	Weak pull-up	Weak pull-up	Active

 Table 6-23.
 External Pin Status during ONCE Mode

8. TS83C51RB2/RC2/RD2 ROM

8.1 ROM Structure

The TS83C51RB2/RC2/RD2 ROM memory is divided in three different arrays:

- the code array:16/32/64 Kbytes.
- the encryption array:64 bytes.
- the signature array:4 bytes.

8.2 ROM Lock System

The program Lock system, when programmed, protects the on-chip program against software piracy.

8.2.1 8.2.1 Encryption Array

Within the ROM array are 64 bytes of encryption array that are initially unprogrammed (all FF's). Every time a byte is addressed during program verify, 6 address lines are used to select a byte of the encryption array. This byte is then exclusive-NOR'ed (XNOR) with the code byte, creating an encrypted verify byte. The algorithm, with the encryption array in the unprogrammed state, will return the code in its original, unmodified form.

When using the encryption array, one important factor needs to be considered. If a byte has the value FFh, verifying the byte will produce the encryption byte value. If a large block (>64 bytes) of code is left unprogrammed, a verification routine will display the content of the encryption array. For this reason all the unused code bytes should be programmed with random values. This will ensure program protection.

8.2.2 Program Lock Bits

The lock bits when programmed according to Table 8-1. will provide different level of protection for the on-chip code and data.

Program Lock Bits				
Security level	LB1	LB2	LB3	Protection Description
1	U	U	U	No program lock features enabled. Code verify will still be encrypted by the encryption array if programmed. MOVC instruction executed from external program memory returns non encrypted data.
2	Ρ	U	U	MOVC instruction executed from external program memory are disabled from fetching code bytes from internal memory, \overline{EA} is sampled and latched on reset.
3	U	Ρ	U	Same as level 1+ Verify disable. This security level is only available for 51RDX2 devices.

Table 8-1.	Program Lock bits

U: unprogrammed P: programmed

8.2.3 Signature bytes

The TS83C51RB2/RC2/RD2 contains 4 factory programmed signatures bytes. To read these bytes, perform the process described in section 8.3.





8.2.4 Verify Algorithm

Refer to Section "Verify algorithm".

9. TS87C51RB2/RC2/RD2 EPROM

9.1 EPROM Structure

The TS87C51RB2/RC2/RD2 EPROM is divided in two different arrays:

- the code array:16/32/64 Kbytes.
- the encryption array:64 bytes.

In addition a third non programmable array is implemented:

• the signature array: 4 bytes.

9.2 EPROM Lock System

The program Lock system, when programmed, protects the on-chip program against software piracy.

9.2.1 Encryption Array

Within the EPROM array are 64 bytes of encryption array that are initially unprogrammed (all FF's). Every time a byte is addressed during program verify, 6 address lines are used to select a byte of the encryption array. This byte is then exclusive-NOR'ed (XNOR) with the code byte, creating an encrypted verify byte. The algorithm, with the encryption array in the unprogrammed state, will return the code in its original, unmodified form.

When using the encryption array, one important factor needs to be considered. If a byte has the value FFh, verifying the byte will produce the encryption byte value. If a large block (>64 bytes) of code is left unprogrammed, a verification routine will display the content of the encryption array. For this reason all the unused code bytes should be programmed with random values. This will ensure program protection.

9.2.2 Program Lock Bits

The three lock bits, when programmed according to Table 9-1.9.2.3, will provide different level of protection for the on-chip code and data.

Program Lock Bits				
Security level	LB1	LB2	LB3	Protection Description
1	U	U	U	No program lock features enabled. Code verify will still be encrypted by the encryption array if programmed. MOVC instruction executed from external program memory returns non encrypted data.
2	Ρ	U	U	MOVC instruction executed from external program memory are disabled from fetching code bytes from internal memory, EA is sampled and latched on reset, and further programming of the EPROM is disabled.
3	U	Р	U	Same as 2, also verify is disabled.
4	U	U	Р	Same as 3, also external execution is disabled.

 Table 9-1.
 Program Lock bits

U: unprogrammed,

P: programmed



60h	FCh	Product name: TS87C51RD2
60h	37h	Product name: TS83C51RC2
60h	B7h	Product name: TS87C51RC2
60h	3Bh	Product name: TS83C51RB2
60h	BBh	Product name: TS87C51RB2
61h	FFh	Product revision number





11.4 DC Parameters for Low Voltage

TA = 0°C to +70°C; V_{SS} = 0 V; V_{CC} = 2.7 V to 5.5 V \pm 10%; F = 0 to 30 MHz. TA = -40°C to +85°C; V_{SS} = 0 V; V_{CC} = 2.7 V to 5.5 V \pm 10%; F = 0 to 30 MHz.

 Table 11-2.
 DC Parameters for Low Voltage

Symbol	Parameter	Min	Тур	Max	Unit	Test Conditions
V _{IL}	Input Low Voltage	-0.5		0.2 V _{CC} - 0.1	V	
V _{IH}	Input High Voltage except XTAL1, RST	0.2 V _{CC} + 0.9		V _{CC} + 0.5	V	
V _{IH1}	Input High Voltage, XTAL1, RST	0.7 V _{CC}		V _{CC} + 0.5	V	
V _{OL}	Output Low Voltage, ports 1, 2, 3, 4, 5 ⁽⁶⁾			0.45	V	I _{OL} = 0.8 mA ⁽⁴⁾
V _{OL1}	Output Low Voltage, port 0, ALE, PSEN (6)			0.45	V	I _{OL} = 1.6 mA ⁽⁴⁾
V _{OH}	Output High Voltage, ports 1, 2, 3, 4, 5	0.9 V _{CC}			V	I _{OH} = -10 μA
V _{OH1}	Output High Voltage, port 0, ALE, PSEN	0.9 V _{CC}			V	I _{OH} = -40 μA
I _{IL}	Logical 0 Input Current ports 1, 2, 3, 4, 5			-50	μA	Vin = 0.45 V
ILI	Input Leakage Current			±10	μA	0.45 V < Vin < V _{CC}
ITL	Logical 1 to 0 Transition Current, ports 1, 2, 3, 4, 5			-650	μA	Vin = 2.0 V
R _{RST}	RST Pulldown Resistor	50	90 (5)	200	kΩ	
CIO	Capacitance of I/O Buffer			10	pF	Fc = 1 MHz TA = 25°C
I _{PD}	Power-down Current		20 ⁽⁵⁾ 10 ⁽⁵⁾	50 30	μΑ	$V_{CC} = 2.0 \text{ V to } 5.5 \text{ V}^{(3)}$ $V_{CC} = 2.0 \text{ V to } 3.3 \text{ V}^{(3)}$
I _{PD}	Power-down Current (Only for TS87C51RD2 S287-xxx Very Low power)		2 ⁽⁵⁾	15	μA	$2.0 \text{ V} < \text{V}_{\text{CC}} < 3.6 \text{ V}^{(3)}$
I _{CC} under RESET	Power Supply Current Maximum values, X1 mode: (7)			1 + 0.2 Freq (MHz) @12MHz 3.4 @16MHz 4.2	mA	$V_{CC} = 3.3 V^{(1)}$
I _{CC} operating	Power Supply Current Maximum values, X1 mode: (7)			1 + 0.3 Freq (MHz) @12MHz 4.6 @16MHz 5.8	mA	V _{CC} = 3.3 V ⁽⁸⁾
l _{CC} idle	Power Supply Current Maximum values, X1 mode: (7)			0.15 Freq (MHz) + 0.2 @12MHz 2 @16MHz 2.6	mA	V _{CC} = 3.3 V ⁽²⁾

Notes: 1. I_{CC} under reset is measured with all output pins disconnected; XTAL1 driven with T_{CLCH} , $T_{CHCL} = 5$ ns (see Figure 11-5.), $V_{IL} = V_{SS} + 0.5$ V,

 $V_{IH} = V_{CC} - 0.5V$; XTAL2 N.C.; $\overline{EA} = RST = Port 0 = V_{CC}$. I_{CC} would be slightly higher if a crystal oscillator used...

2. Idle I_{CC} is measured with all output pins disconnected; XTAL1 driven with T_{CLCH}, T_{CHCL} = 5 ns, V_{IL} = V_{SS} + 0.5 V, V_{IH} = V_{CC} - 0.5 V; XTAL2 N.C; Port 0 = V_{CC}; \overline{EA} = RST = V_{SS} (see Figure 11-3.).

Power-down I_{CC} is measured with all output pins disconnected; EA = V_{SS}, PORT 0 = V_{CC}; XTAL2 NC.; RST = V_{SS} (see Figure 11-4.).



Part Number	Memory size	Supply Voltage	Temperature Range	Max Frequency	Package	Packing
TS83C51RD2-MCA						
TS83C51RD2-MCB	-					
TS83C51RD2-MCE	-					
TS83C51RD2-MIA						
TS83C51RD2-MIB						
TS83C51RD2-MIE						
TS83C51RD2-LCB						
TS83C51RD2-LCE						
TS83C51RD2-LIA			OBSOLE	TE		
TS83C51RD2-LIB						
TS83C51RD2-LIE						
TS83C51RD2-VCA						
TS83C51RD2-VCB						
TS83C51RD2-VCE						
TS83C51RD2-VIA						
TS83C51RD2-VIB						
TS83C51RD2-VIE						
				-		
AT83C51RD2-3CSUM	ROM 64k Bytes	5V	Industrial & Green	40 MHz (20 MHz X2)	PDIL40	Stick
AT83C51RD2-SLSUM	ROM 64k Bytes	5V	Industrial & Green	40 MHz (20 MHz X2)	PLCC44	Stick
AT83C51RD2-RLTUM	ROM 64k Bytes	5V	Industrial & Green	40 MHz (20 MHz X2)	VQFP44	Tray
AT83C51RD2-3CSUL	ROM 64k Bytes	3-5V	Industrial & Green	30 MHz (20 MHz X2)	PLCC44	Stick
AT83C51RD2-SLSUL	ROM 64k Bytes	3-5V	Industrial & Green	30 MHz (20 MHz X2)	VQFP44	Tray
AT83C51RD2-RLTUL	ROM 64k Bytes	5V	Industrial & Green	40 MHz (30 MHz X2)	PDIL40	Stick

13. Package Drawings

13.1 PLCC44



	1	۹M ·	ΙN	СН			
A	4.20	4.57	. 165	. 180			
A1	2, 29	3.04	. 090	. 120			
D	17.40	17.65	. 685	. 695			
D1	16.44	16.66	. 647	. 656			
D5	14.99	16.00	. 590	. 630			
E	17.40	17.65	. 685	. 695			
E1	16.44	16.66	. 647	. 656			
E5	14.99	16.00	. 590	. 630			
e	1.27	BSC	. 050	BSC			
G	1.07	1.22	. 042	. 048			
н	1.07	1.42	. 042	. 056			
J	0.51	-	. 020	-			
К	0.33	0.53	. 013	. 021			
Nd	1	1	1	1			
Ne	1	11		1			
P	KG STD	00					





13.2 PDIL40



			I.			
	ММ		I NCH			
A	-	5.08	-	. 200		
A1	0.38	-	. 015	-		
A2	3.18	4. 95	. 125	. 195		
В	0.36	0.56	. 014	. 022		
B1	0.76	1. 78	. 030	. 070		
С	0.20	0.38	. 008	. 015		
D	50.29	53. 21	1.980	2.095		
E	15.24	15.87	. 600	. 625		
E1	12.32	14.73	. 485	. 580		
e	2. 54	B. S. C	. 100	B. S. C		
еА	15.24	B. S. C	. 600	B. S. C		
еB	-	1 7. 78	_	. 700		
L	2. 93	3. 81	. 115	. 150		
D1	0.13	-	. 005	-		
P	KG STD	02				



13.4 VQFP64

SQUARE GULL WING (1.4 mm)





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